

Innovative DC/DC Power Modules

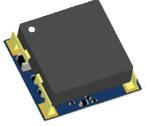
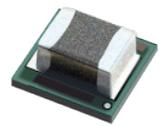
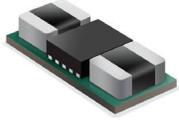


Overview

TI's broad range of DC/DC power modules are designed specifically to help designers get to market faster with validated, high performance solutions. In a single package, these power modules integrate inductors, FETs, compensation, and other passive components to reduce development time for design and verification, and speed up time to market with proven reliability.

To browse the entire portfolio and learn more on the latest products, visit: ti.com/powermodules

Featured Products

<p>TPSM846C23</p> 	<ul style="list-style-type: none"> • 4.5V to 15V_{IN} • 35A Output; Parallel for 70A • PMBus v1.3 Command Set • 15 x 16 x 6.5mm • TPSM846C24 for Non-PMBus 	<p>TPS82130/40/50</p> 	<ul style="list-style-type: none"> • 3V to 17V_{IN} • 1, 2 and 3A Output Current Options • 0.9 to 5V_{OUT} • Tiny 2.8 x 3.0 x 1.5mm Package • Light Load Efficient
<p>TPSM84203/05/12</p> 	<ul style="list-style-type: none"> • 4.5 to 28V_{IN} • Fixed 3.3V, 5V and 12V Outputs • 1.5A Output Current • Low EMI with Spread Spectrum • Pin-Pin Wth TO-220 Package 	<p>TPSM82480</p> 	<ul style="list-style-type: none"> • 2.4 to 5.5V_{IN} • Tiny 3.6 x 7.9 x 1.5mm Package • 0.6 to 5.0V_{OUT} at 6A • Light Load Efficiency or Fixed Freq.
<p>LMZM33602/03</p> 	<ul style="list-style-type: none"> • 4.0 to 36V_{IN} • 2.4 to 18V_{OUT} • 2A/3A Output Current • 7 x 9 x 3.8mm Package • Forced PWM and Low EMI 	<p>LMZM23600/1</p> 	<ul style="list-style-type: none"> • 4V to 36V_{IN} • 1A and 0.5A Output Current Options • Fixed 5V, 3.3V and Adj V_{OUT} to 15V • Tiny 3.8 x 3.0 x 1.6mm Package
<p>TPSM84A21/2</p> 	<ul style="list-style-type: none"> • 8V to 14V_{IN} • 10A Output Current • 0.55 to 2.05V_{OUT} • Only One External Component • 15 x 9 x 2.3mm Package 	<p>TPSM84824/624/424</p> 	<ul style="list-style-type: none"> • 4.5 to 17V_{IN} • 8A, 6A and 4A Output Current • 0.6V to 10V_{OUT} • 7.5 x 7.5 x 5.3mm Package • TurboTrans™ Fast Transient Response

Why Power Modules?

Smaller Size

LM46002



288mm²

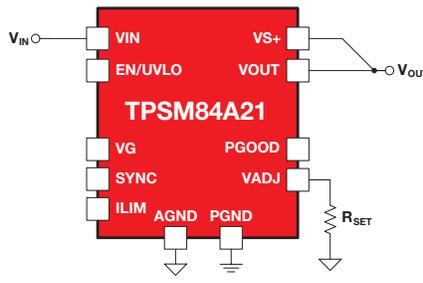
LMZ36002



196mm²

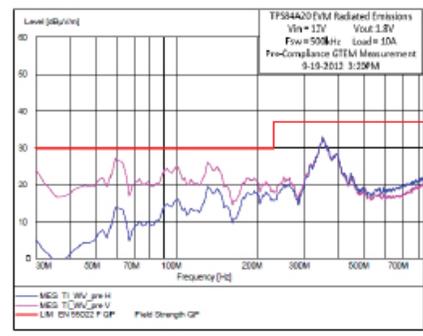
- Module smaller vs discrete

Simple Solutions



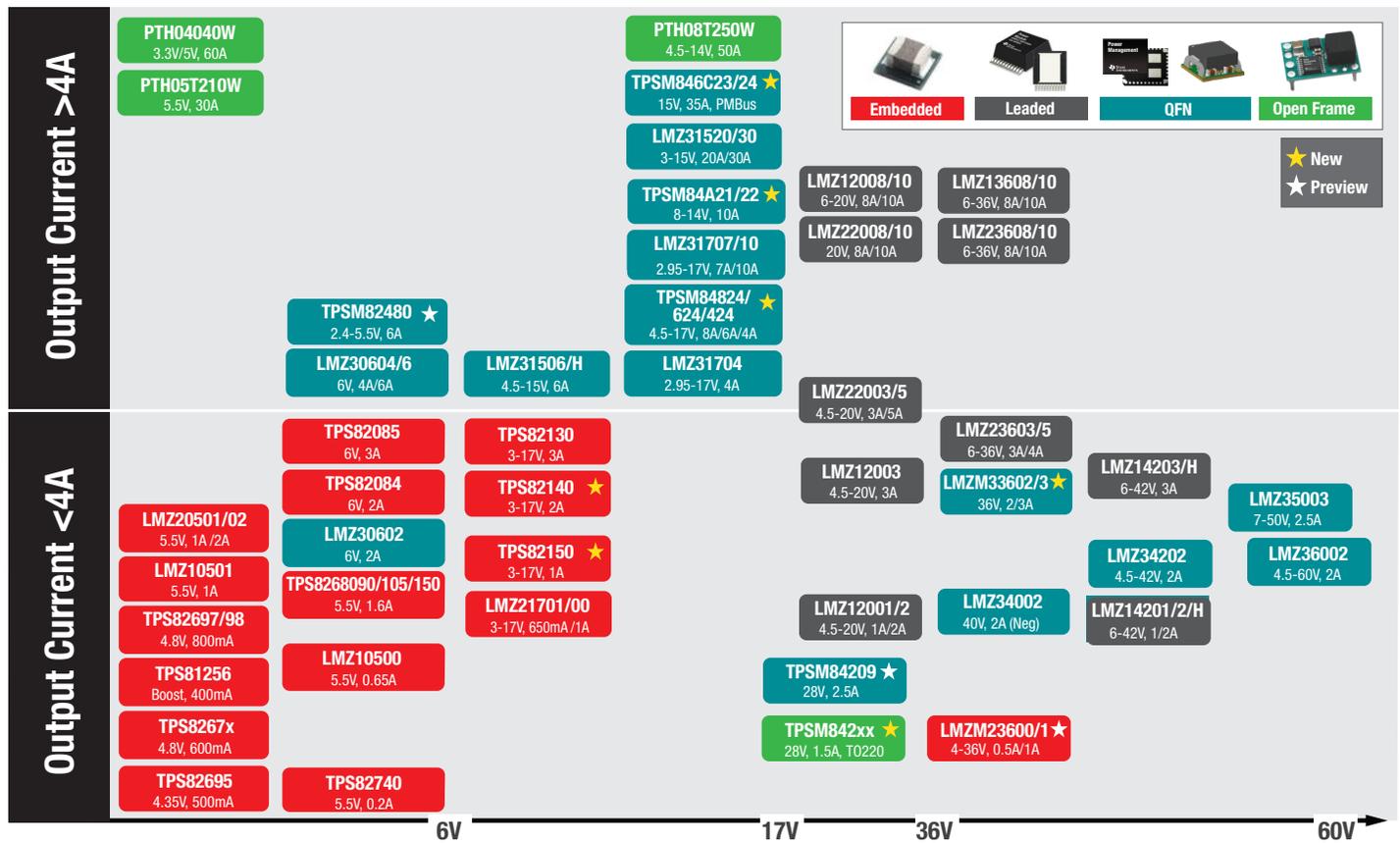
- Minimal components

Low EMI

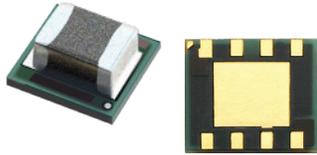
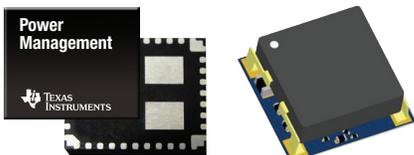
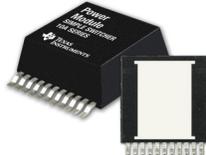


- Tested EMI performance

TI's Power Module Portfolio



TI Module Packages (Select)

	Embedded	QFN	Leaded
Package Outline	BGA / LGA (QFN-like)	QFN Style	TO-Style
Description	 <p>LGA QFN Pinless Package Embedded Die in FR Laminate (LGA or BGA Pads). MSL2/3 Highest Density Package</p>	 <p>QFN-Style Pinless Package Single Copper Leadframe MSL3 Size Optimized Package Excellent Thermals</p>	 <p>TO-Style Pinned Package Dual Copper Leadframe 7 and 11 Pin Versions. MSL3 Large Single Thermal Pad Easy to Use</p>

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